2SB1030, 2SB1030A

Silicon PNP epitaxial planar type

For low-frequency amplification

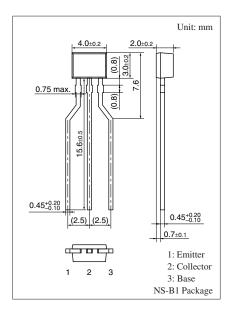
Complementary to 2SD1423 and 2SD1423A

■ Features

- Optimum for high-density mounting
- Allowing supply with the radial taping

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage	2SB1030	V_{CBO}	-30	V
(Emitter open)	2SB1030A		-60	
Collector-emitter voltage	2SB1030	V _{CEO}	-25	V
(Base open)	2SB1030A		-50	
Emitter-base voltage (Coll	V_{EBO}	-7	V	
Collector current	I_C	- 0.5	A	
Peak collector current	I_{CP}	-1	A	
Collector power dissipation	P _C	300	mW	
Junction temperature	T_{j}	150	°C	
Storage temperature	T_{stg}	-55 to +150	°C	



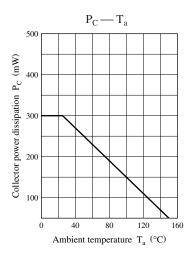
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

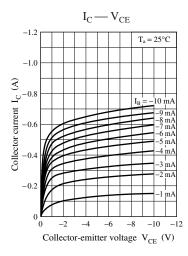
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage 2SE	1030 V _{CBO}	$I_C = -10 \ \mu A, I_E = 0$	-30			V
(Emitter open) 2SB	1030A		-60			
Collector-emitter voltage 2SE	31030 V _{CEO}	$I_C = -2 \text{ mA}, I_B = 0$	-25			V
(Base open) 2SB	1030A		-50			
Emitter-base voltage (Collector o	pen) V _{EBO}	$I_E = -10 \ \mu A, \ I_C = 0$	-7			V
Collector-base cutoff current (Emitter	open) I _{CBO}	$V_{CB} = -20 \text{ V}, I_E = 0$			- 0.1	μΑ
Collector-Emitter cutoff current (Base	open) I _{CEO}	$V_{CE} = -20 \text{ V}, I_{B} = 0$			-1	μΑ
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -10 \text{ V}, I_{C} = -150 \text{ mA}$	85		340	
	h _{FE2}	$V_{CE} = -10 \text{ V}, I_{C} = -500 \text{ mA}$	40			
Collector-emitter saturation volta	ge V _{CE(sat)}	$I_C = -300 \text{ mA}, I_B = -30 \text{ mA}$		- 0.35	- 0.60	V
Transition frequency	f_T	$V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circu	C _{ob}	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		3.5	15.0	pF

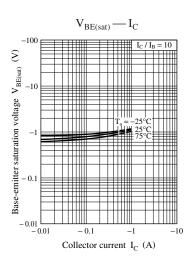
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

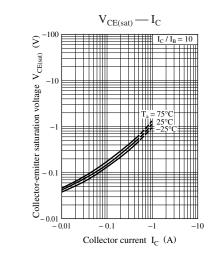
2. *: Rank classification

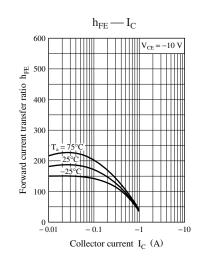
Rank	Q	R	S	
$h_{\rm FE1}$	85 to 170	120 to 240	170 to 340	

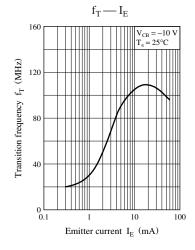


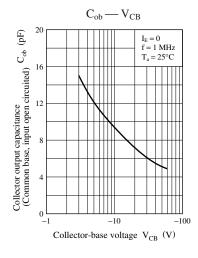


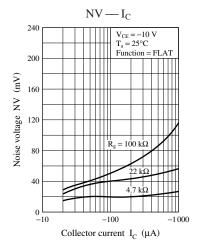












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